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JRW

Docket No. 51565
Express Mil Label No. EV755070212US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Seita et al.

SERIAL NO. 10/696,552 GROUP: 1775

FILED: October 29, 2003 EXAMINER: M. Lavilla

FOR: FORMALDEHYDE-FREE ELECTROLESS COPPER PLATING
PROCESS AND SOLUTION FOR USW IN THE PROCESS

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Applicants are in receipt of the Office Action dated October 5, 2006. Please amend the above-identified application as follows.

A listing of pending claims begins on page 2 of this paper.

Remarks being on page 5 of this paper.